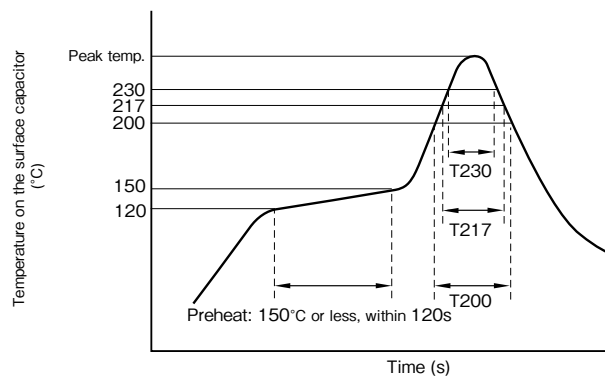


■ Recommended soldering method (series DS, DSK, DVN, DVL)

Reflow soldering conditions.

Profile



T200 : Duration while capacitor head temperature exceeds 200°C (s)

T217 : Duration while capacitor head temperature exceeds 217°C (s)

T230 : Duration while capacitor head temperature exceeds 230°C (s)

The measurement temperature point is the case top

Series	Size	Peak temp. (5s Max)	T230	T217	T200	Times
DS DSK	φ4.8 to φ6.8	250°C Max	Within 20s	Within 30s	Within 40s	2 Max
DVN DVL	φ12.5	260°C Max	Within 20s	Within 30s	Within 50s	2 Max

Attention : Carry out soldering work at low temperature and in the shortest time within above conditions.

Do NOT reflow solder, when cell voltage is above 0.3V.

*Please consult with us about reflow soldering conditions other than the above.